



Product Change Notification / LIAL-19BORP399

Date:

28-Apr-2021

Product Category:

Microprocessors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3700.005 Final Notice: Qualification of a new components U2 and U6 for ATSAMA5D27-WLSOM1 Atmel catalog part number available in 188L module (40.8x40.8x3.3mm) package at MMT assembly site.

Affected CPNs:

[LIAL-19BORP399_Affected_CPN_04282021.pdf](#)

[LIAL-19BORP399_Affected_CPN_04282021.csv](#)

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of a new components U2 and U6 for ATSAMA5D27-WLSOM1 Atmel catalog part number available in 188L module (40.8x40.8x3.3mm) package at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
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ATSAMA5D27-WLSOM1 module package	Using an old version component U2 with an old Chip ID 0x8A5C08C2 and U6	Using a new version component U2 with a new Chip ID 0x8A5C08C4 and U6
	See attached photo for U2 and U6 location	

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on time delivery and performance by qualifying a new components U2 and U6 for ATSAMA5D27-WLSOM1 Atmel catalog part number.

Change Implementation Status:In Progress.

Estimated First Ship Date:June 15, 2021 (date code: 2025)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	April 2021					-	June 2021					
	14	15	16	17	18		>	23	24	25	26	27
Qual Report Availability					X							
Final PCN Issue Date					X							
Estimated Implementation Date									X			

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:April 28, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on June 15, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_LIAL-19BORP399_Qual Report.pdf](#)

[PCN_LIAL-19BORP399_Components_location.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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LIAL-19BORP399 - CCB 3700.005 Final Notice: Qualification of a new components U2 and U6 for ATSAMA5D27-WI
Atmel catalog part number available in 188L module (40.8x40.8x3.3mm) package at MMT assembly site.

Affected Catalog Part Numbers(CPN)

ATSAMA5D27-WLSOM1

LSOM1



MICROCHIP

QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN#: LIAL-19BORP399

Date

August 08, 2019

**Qualification of a new components U2 and U6 for
ATSAMA5D27-WLSOM1 Atmel catalog part number available in
188L module (40.8x40.8x3.3mm) package at MMT assembly site.**



MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose	Qualification of a new components U2 and U6 for ATSAMA5D27-WLSOM1 Atmel catalog part number available in 188L module (40.8x40.8x3.3mm) package at MMT assembly site.
CCB #	3700.005
QUAL ID	Q19118
MP CODE	3410H7LXBR01
PART No.	ATSAMA5D27-WLSOM1
LOT No.	E194AAP1.1, E194AEG1.1, E194AEH1.1
Bonding No.	BDM-002019_revE



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Lot No.	Load (Modules)
E194AAP1.1	80
E194AEG1.1	80
E194AEH1.1	80

Result

Pass

Fail

WLSOM module (ATSAMA5D27-WLSOM1) assembled by MMT is qualified the Moisture/ Reflow Sensitivity Classification Level 3 at 245°C reflow temperature per IPC/JEDEC J-STD-020E standard.



MICROCHIP

PACKAGE QUALIFICATION REPORT

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	QTY (Acc)	Def/SS	Result	Remark
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Bake 150°C, 24 hrs System: DESPATCH 30°C/60%RH Moisture Soak 192 hrs. System: ENVIROTRONIC Model : SH3 3x Convection-Reflow 245 +0/-5°C System: ChipFlo-4 Electrical test: MMT	IPC/JEDEC JESD22-A113 J-STD-020	105	0/105		
High Temperature Storage (HTS)	Bake 150°C, System: BLUE-M Read-point 504, 1008 hours Electrical test: MMT	JESD22-A103	27	0/27 0/27	Pass Pass	
Unbiased HAST	Unbiased HAST 130°C/85%RH, Read-point 96 hrs System: HIRAYAMA Model : PC422R7 Electrical test: MMT	JESD22-A118	30	0/30	Pass	
Temp Cycle	-40/125°C, System: VOTSCH Read-point 500 cycles Read-point 1,000 cycles Electrical test: MMT	JESD22-A104	29	0/29 0/29	Pass	
Unbiased Temperature/ Humidity	Unbiased Temp / Humidity 85°C/85%RH, Read-point 500, 1000 hours System: ENVIROTRONIC Model : SH3 Electrical test: MMT	CCB# 3766	30	0/30 0/30	Pass Pass	

CCB 3700.005
PCN#: LIAL-19BORP399

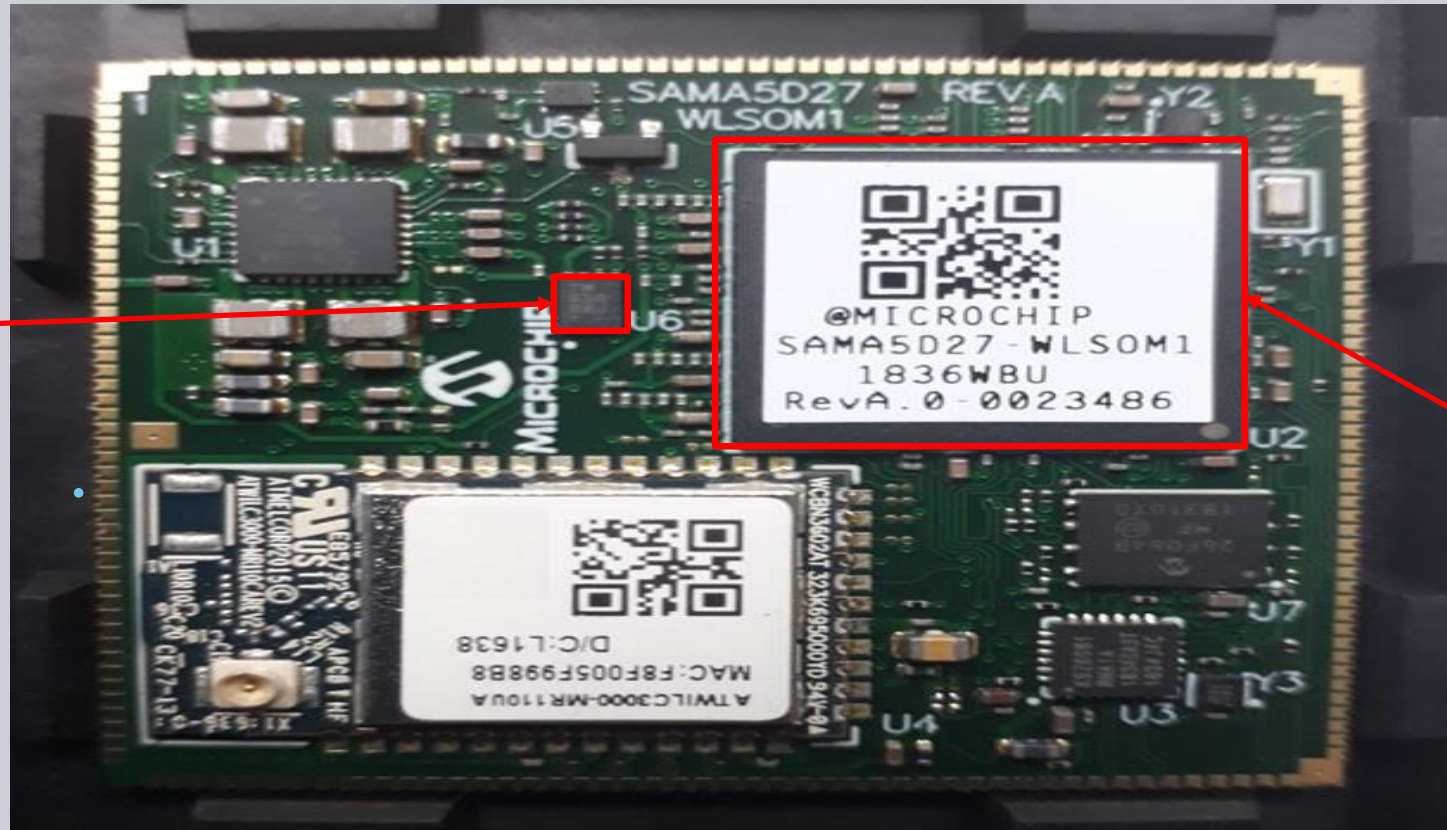


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U2 and U6 Components Location



U6 Component

U2 Component